

# Corrosion of Electronics: Use of Accelerated Testing Predict Reliability

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Sandia National Laboratories



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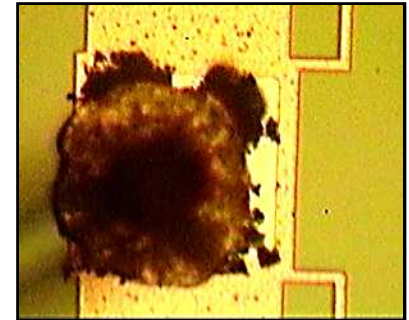
# What is corrosion?

## Environmental degradation of materials

### ➤ Aqueous (general & localized attack)

- electrochemical
- oxidation / reduction

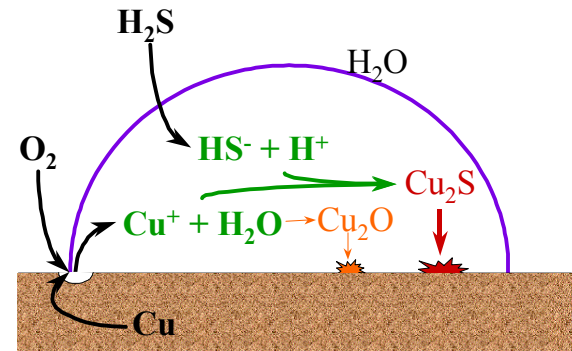
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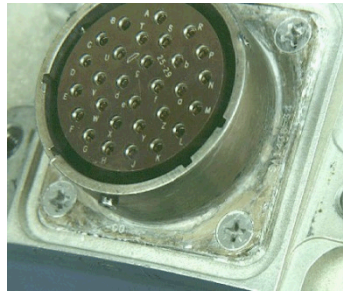
### ➤ Atmospheric

- gas-metal reaction (slow)
- condensed phase electrochemical
- pollutant gasses (ppt levels of  $\text{H}_2\text{S}$ ,  $\text{NO}_2$ ,  $\text{Cl}_2$  ...)

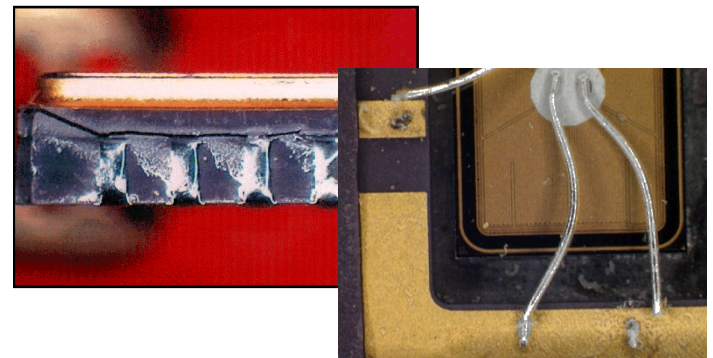
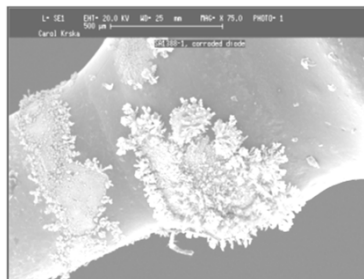
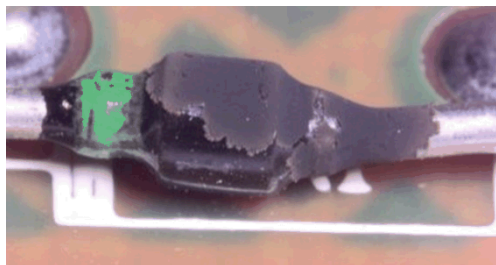
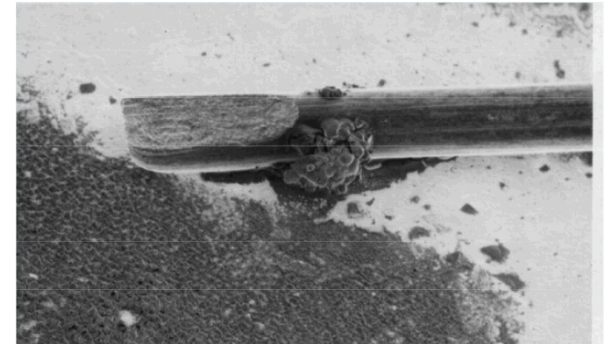
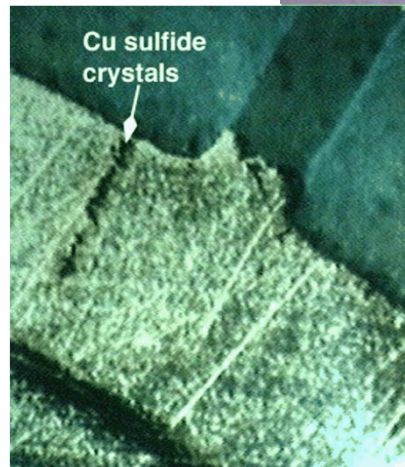
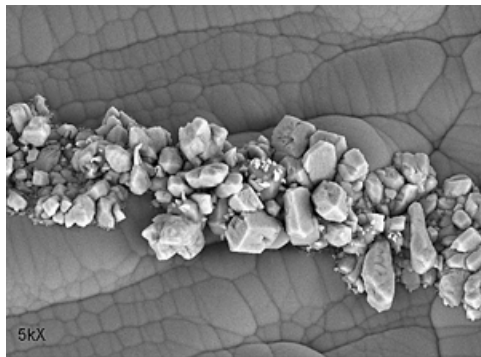
Use



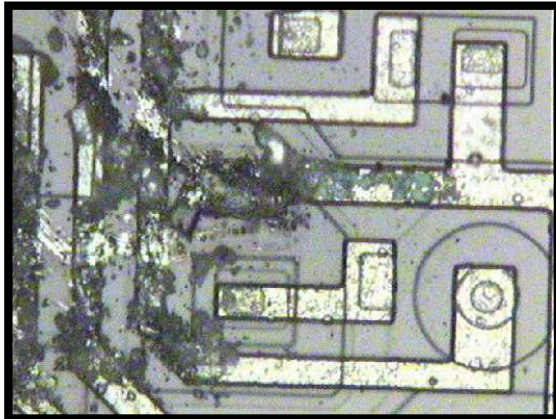
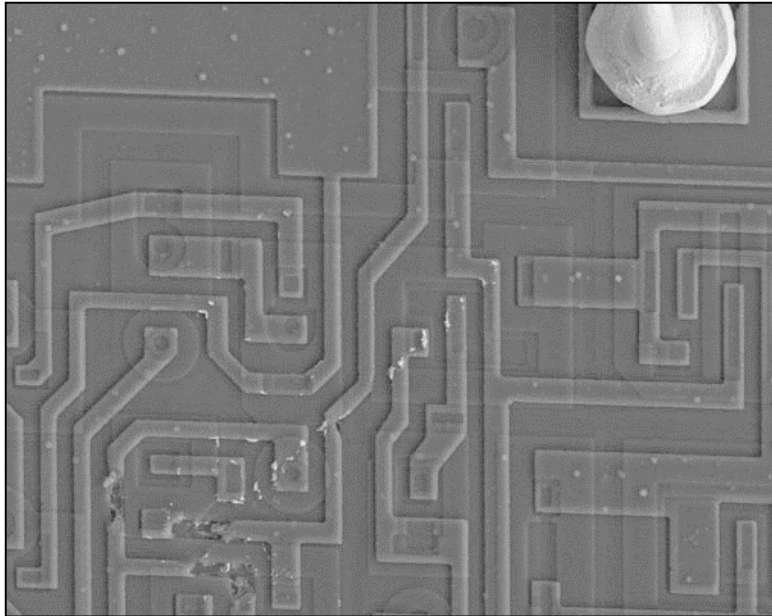
# Corrosion normally occurs due to defects or unexpected environments



Cruise missile  
fuel line

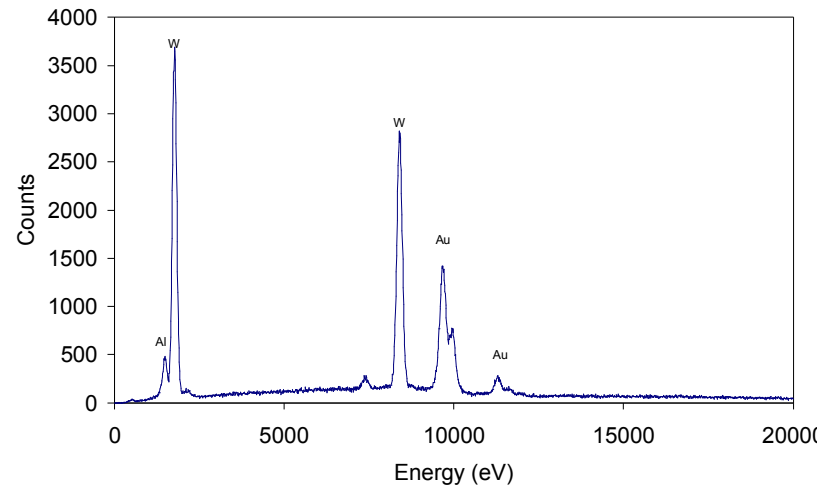


# A plastic encapsulated IC failed after 5 years in dormant storage.



## Defects:

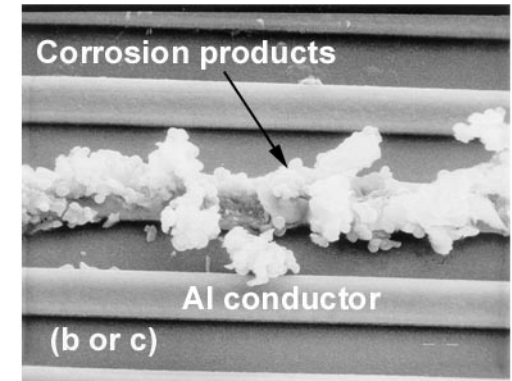
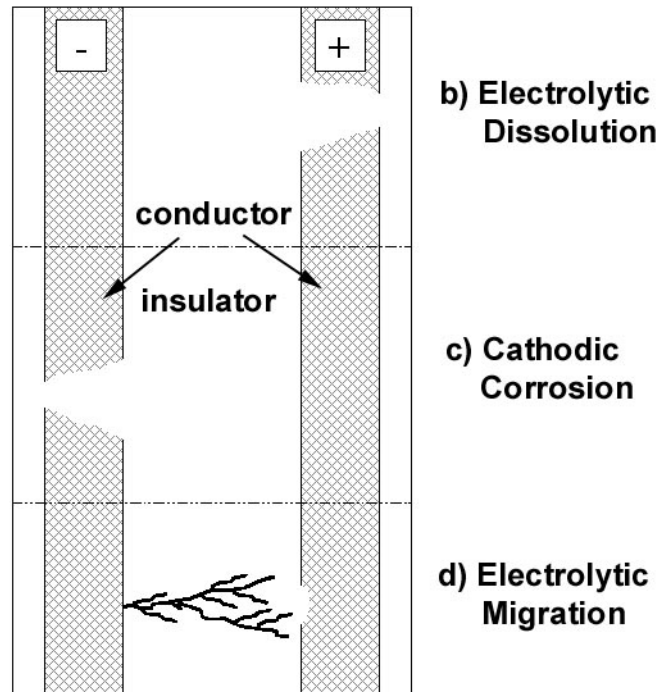
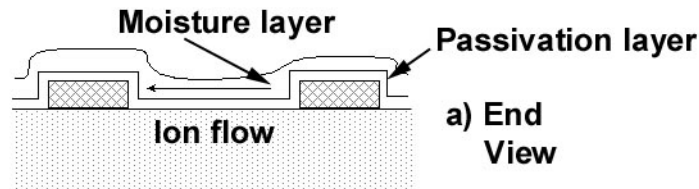
- Damaged passivation
- Au (galvanic couple)





# Several non-traditional corrosion mechanisms exist in microelectronics that involve electrical bias

- **Electrolytic dissolution**
- **Cathodic corrosion (alkalization)**
- **Electrolytic migration**



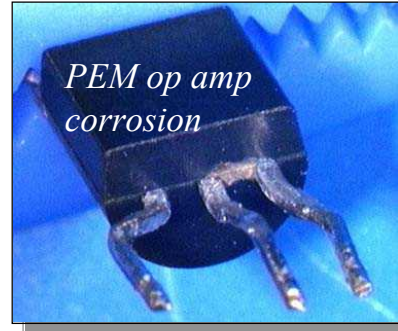
c) Cathodic Corrosion

d) Electrolytic Migration



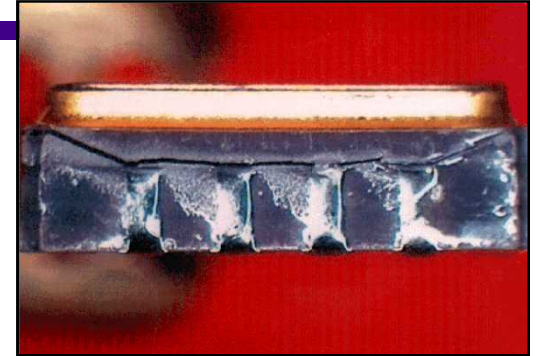
# Conditions required for electrolytic migration

- Applied voltage
  - powered system
- Susceptible alloy
  - Ag used in ground plane
  - Solder
  - Copper
- Conductive surface
  - flux residue (activator)
- Electrolyte
  - High humidity
    - Temperature cycling
  - Seacoast environment (NaCl)



# Corrosive environments can contact metallization features

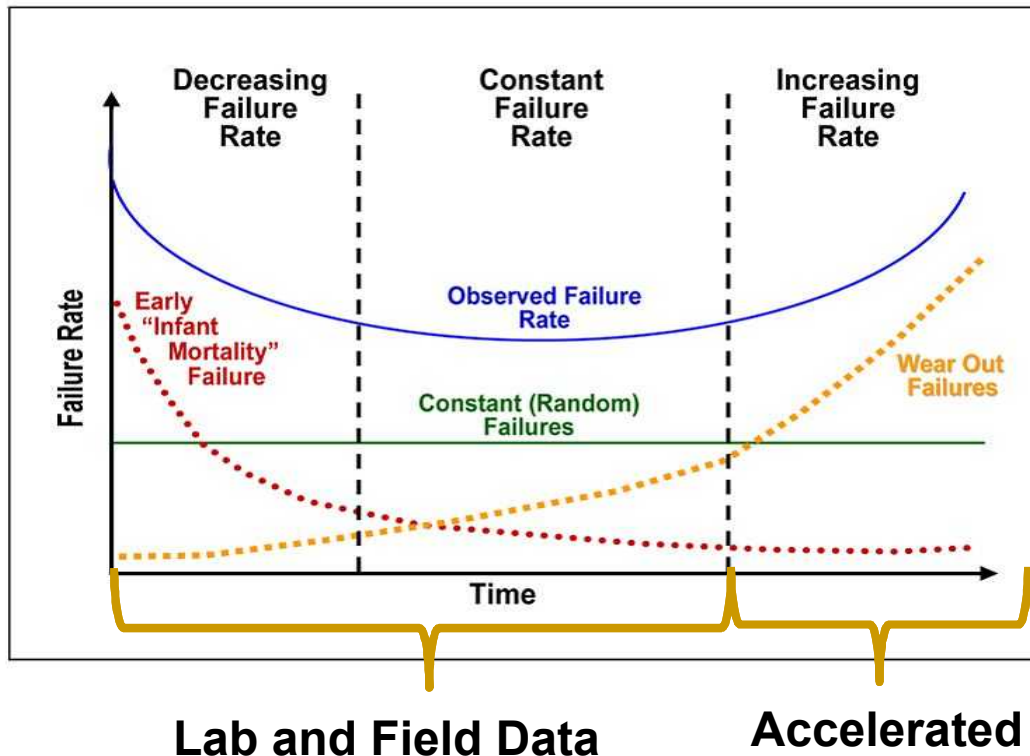
- **Breach in hermetic packaging in CHP**
- **Use of encapsulants in PEMs with high water permeability**
- **Specific unintended exposures (e.g., military)**
  - **high T, RH, [Cl<sup>-</sup>] possible**



# Materials Degradation Affects Reliability

Probability of failure-free performance, item's useful life, or a specified timeframe specified environmental duty-cycle conditions.

Reliability  Cost

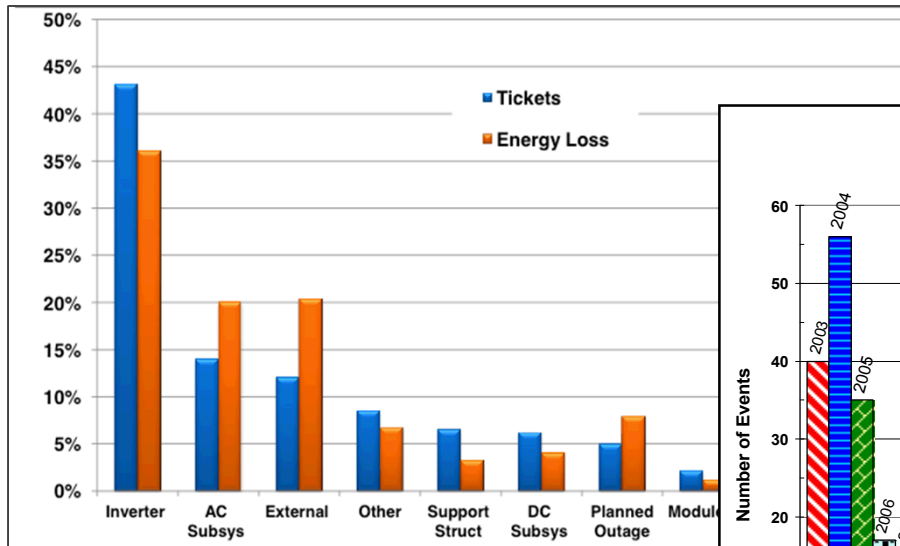


**Accelerated testing plays a key role in determining reliability**

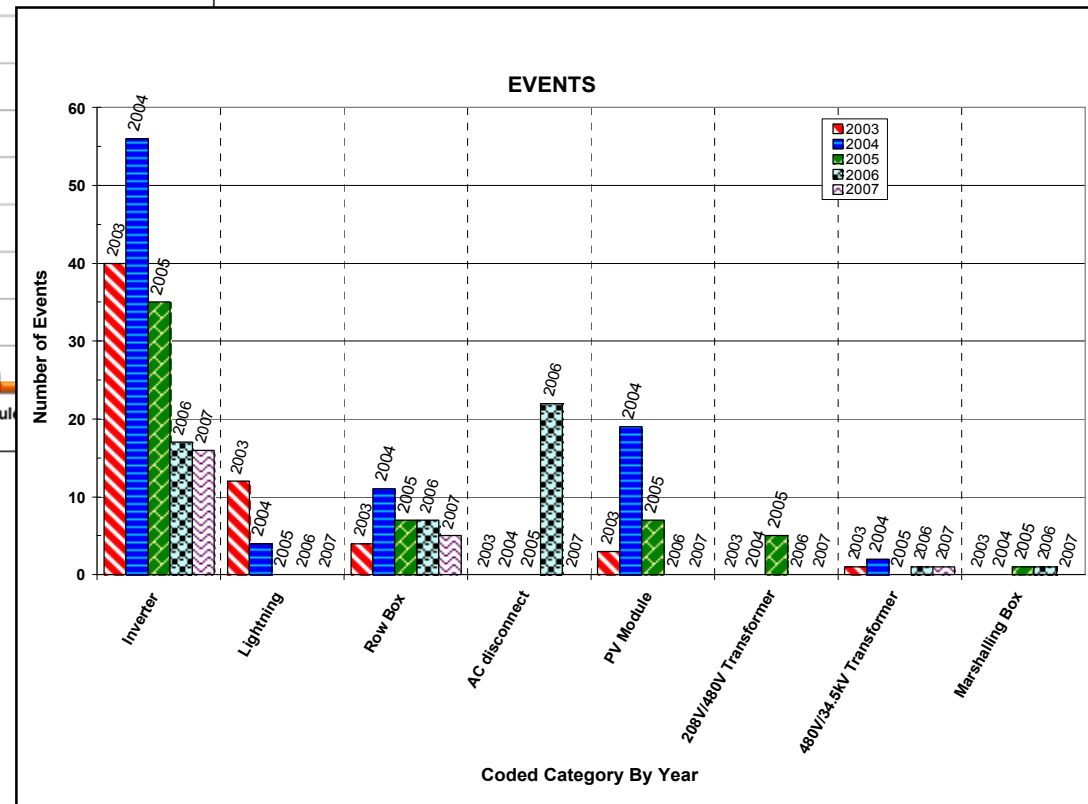
- **Must be applicable to failure modes**
  - **Reproduce field failures**
- **Acceleration factor**
  - **Range of stresses**
  - **Long term tests**



# The inverter is a significant contributor to reliability issues



Sun Edison – Owner/Operator (A. Golnas, “PV System Reliability: An Operator’s Perspective,” in 38th Photovoltaic Specialists Conference, Austin, TX, Jun. 2012, pp. 1–32.)



Tucson Electric Springerville Plant.  
Sandia Study

# What is ALT & why?

## What?

- Component life tests
- High stresses
  - Single or combined
  - Activate “appropriate” failure modes
  - Measureable
- Time compression (cyclic stresses)
- Failure analysis

## Why?

- Time
- Full system is expensive and complicated

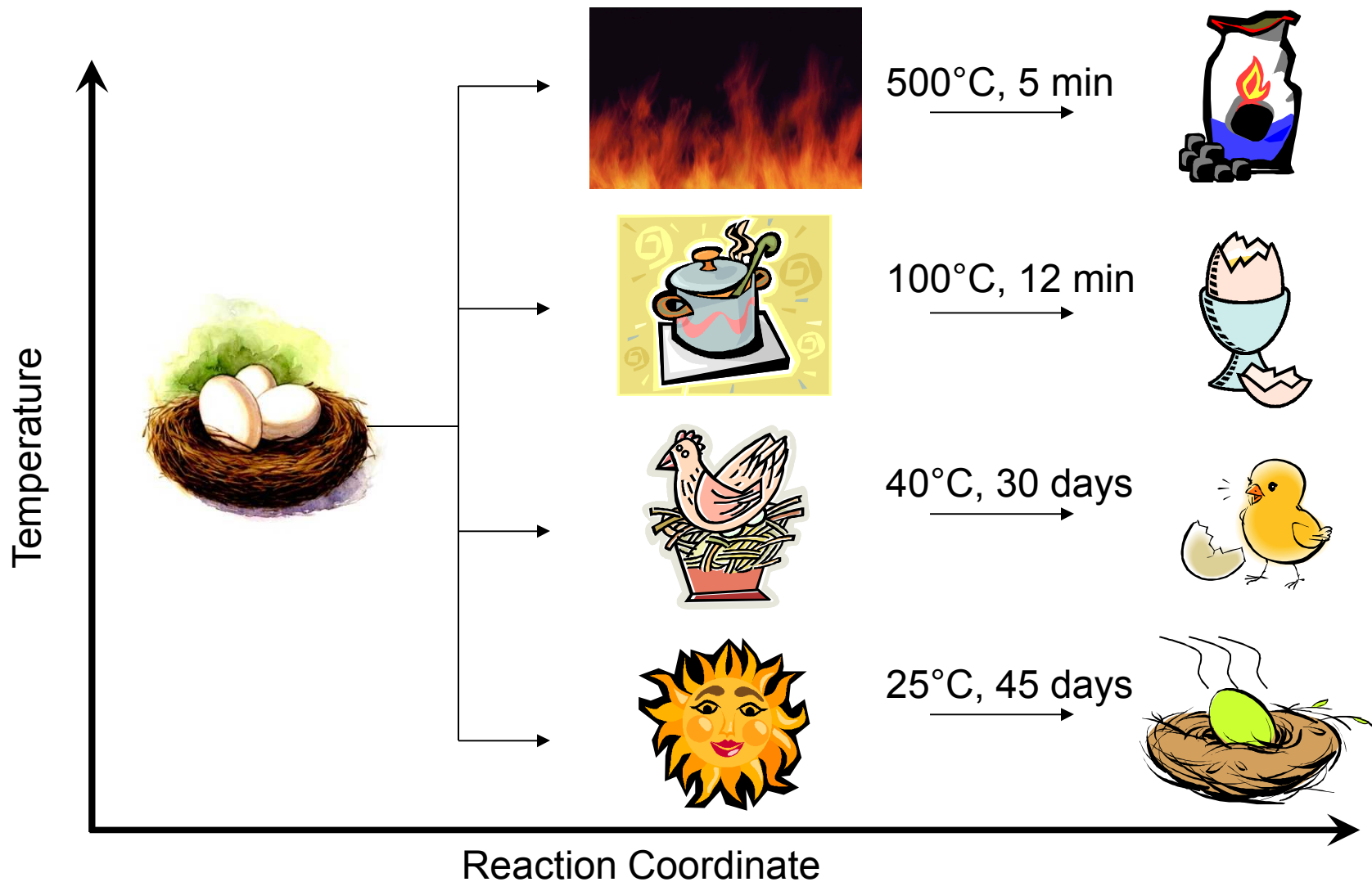
# Failure Modes for Crystalline Silicon

(John Wolgemuth – BP Solar)

- Broken interconnects
- Broken Cells
- Corrosion
- Delamination and/or loss of elastic properties
- Encapsulant discoloration
- Solder bond failures
- Broken glass
- Hot Spots
- Ground faults
- Junction box and module connection failures
- Structural failures

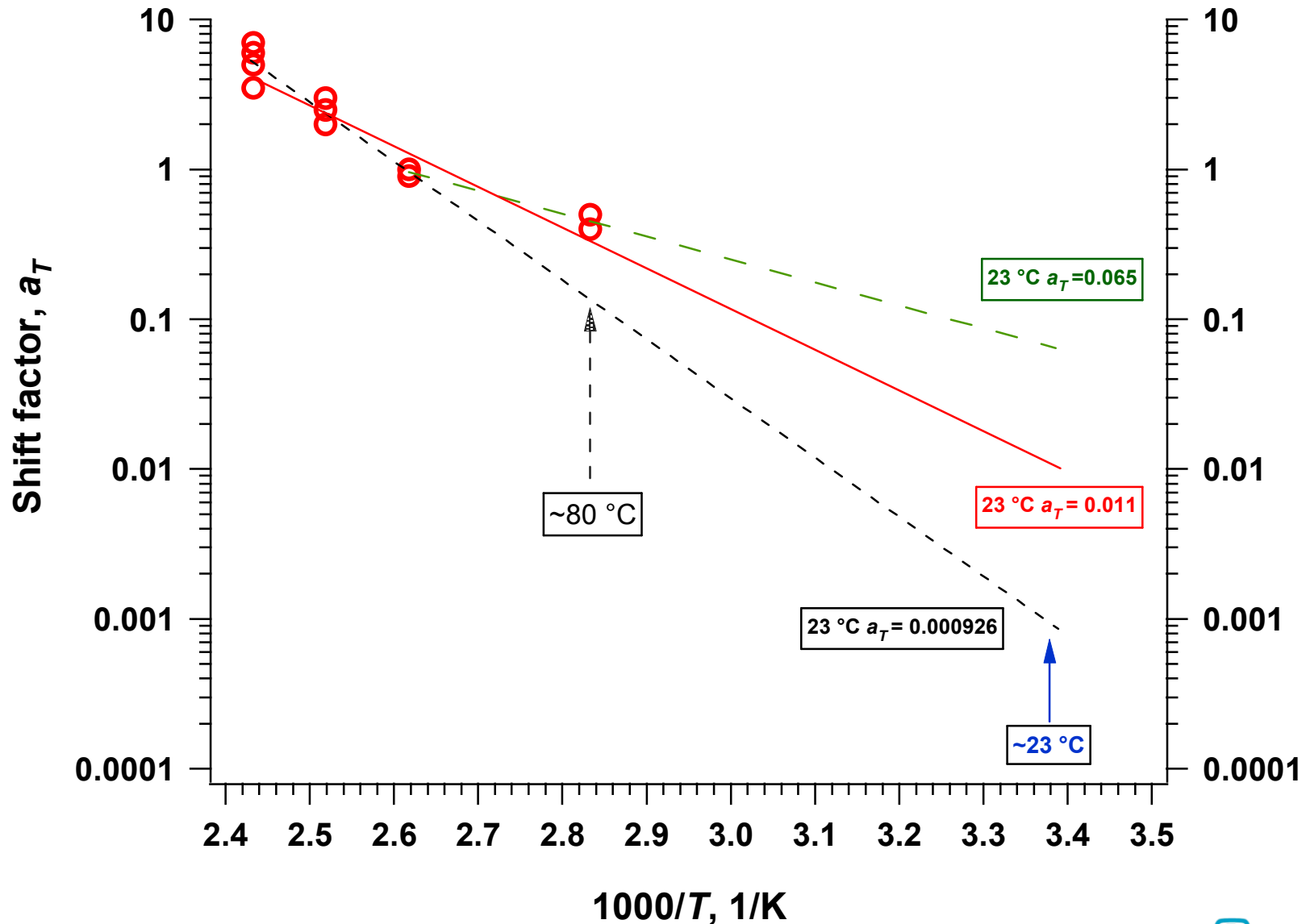
Would you expect a single test to capture all of the expected failure modes?

# It is important to understand the degradation mechanism and select appropriate stress level

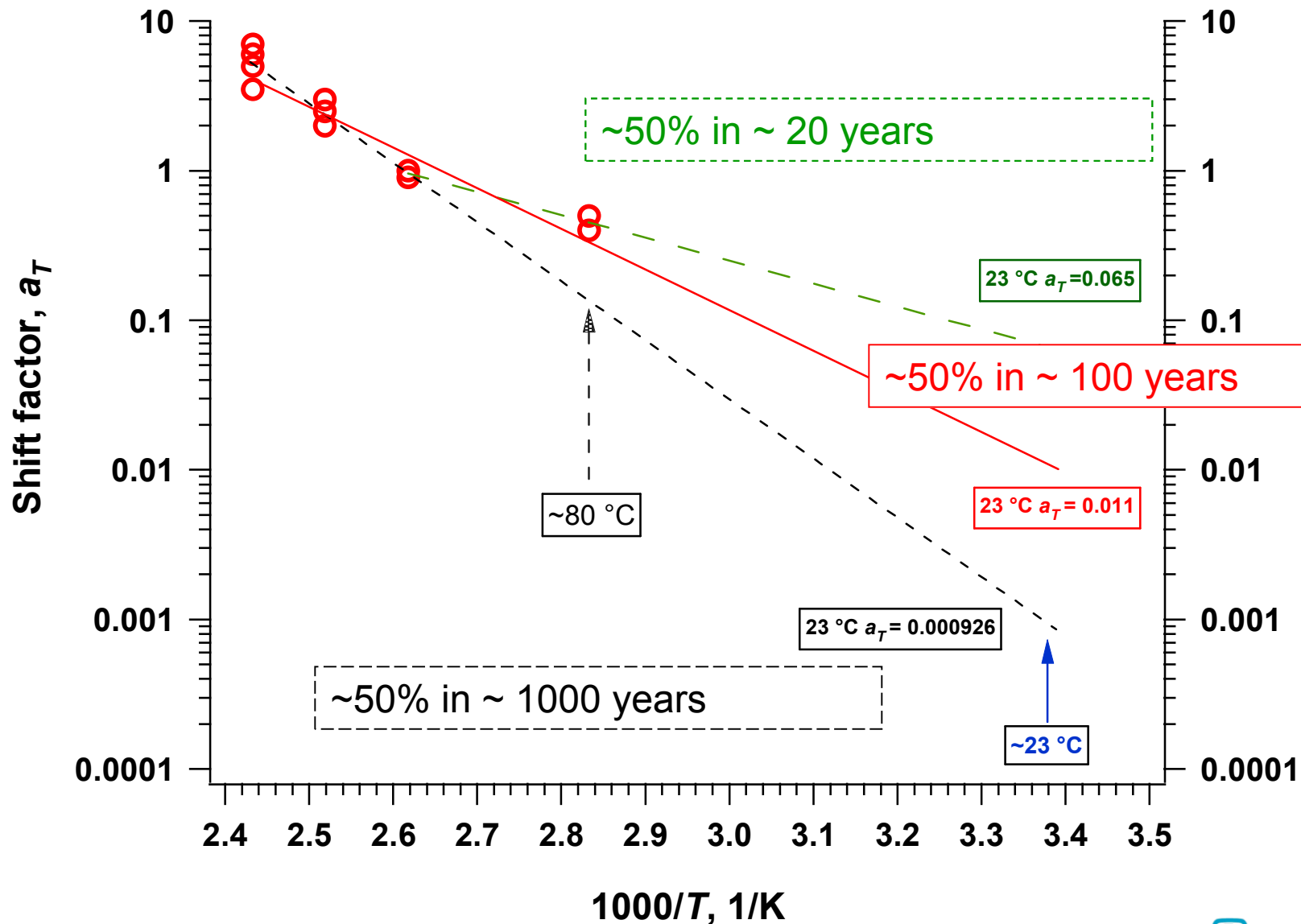




High T data are extrapolated to “use” conditions  
(room temperature)



# How you extrapolate can influence lifetime predictions.



# Two approaches to accelerated testing are used throughout industry

## ➤ Qualitative Accelerated Tests

- HALT tests
  - HAST tests
  - HASS tests
- } Small sample size  
Severe level of stress

Increase reliability  
(product improvement)  
Qualify new designs  
Design quantitative ALT

Reliability under normal  
use conditions

## ➤ Quantitative Accelerated Life Tests

- Controlled application of accelerated stress
- Produces acceleration factors (AF)
  - Usage rate acceleration  
(Time compression)
  - Overstress acceleration

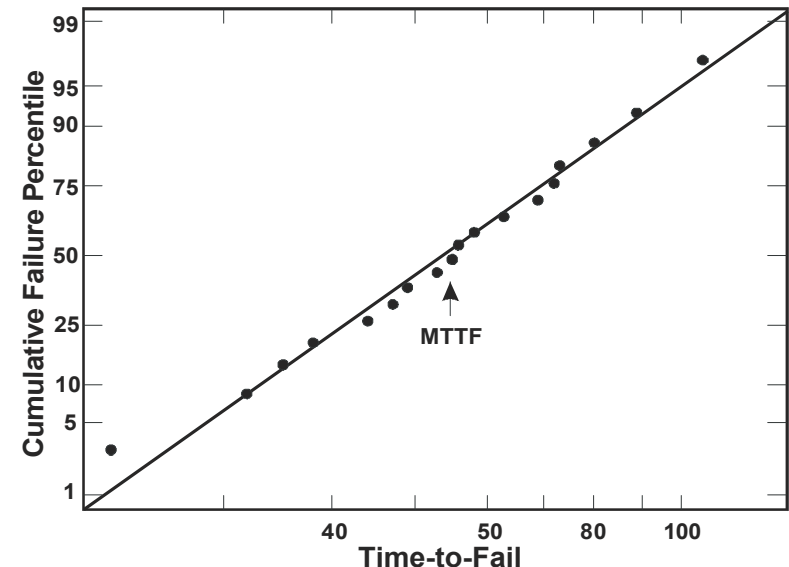
Used to determine TTF  
Determine reliability

Long Time  
Need degradation / failure  
mechanisms

The Goal of an ALT program is to produce acceleration factors

- Often empirical correlations
- Limited root-cause analyses

$$AF = \left( \frac{MTTF_{\text{field}}}{MTTF_{\text{test}}} \right)$$



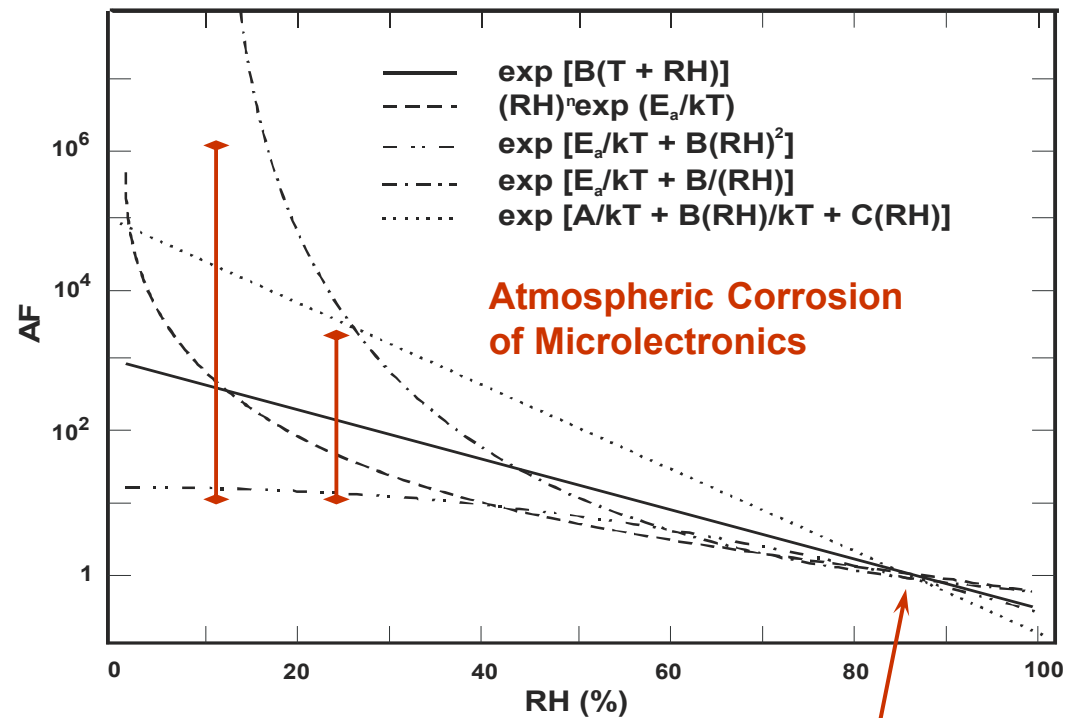
$$AF = \exp \left[ \frac{E_a}{k} \left( \frac{1}{T_o} - \frac{1}{T} \right) \right] \left( \frac{RH}{RH_o} \right)^n \left( \frac{a+bV}{a+bV_o} \right)$$



# ALT must capture valid degradation / failure mechanisms

## Example:

- Five recognized models for corrosion in micro-electronics
- All agree at 85%RH
- Disagreement at 10%-30% prevents uniform application of either model



# Acceleration factors depend on the stress characteristics

## ➤ Thermal (Arrhenius)

- Activation energy
- Verify no mechanism change
- Bin damage by time at temperature

## ➤ $\Delta T$

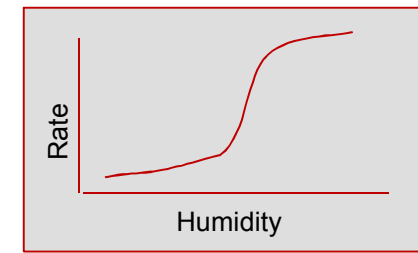
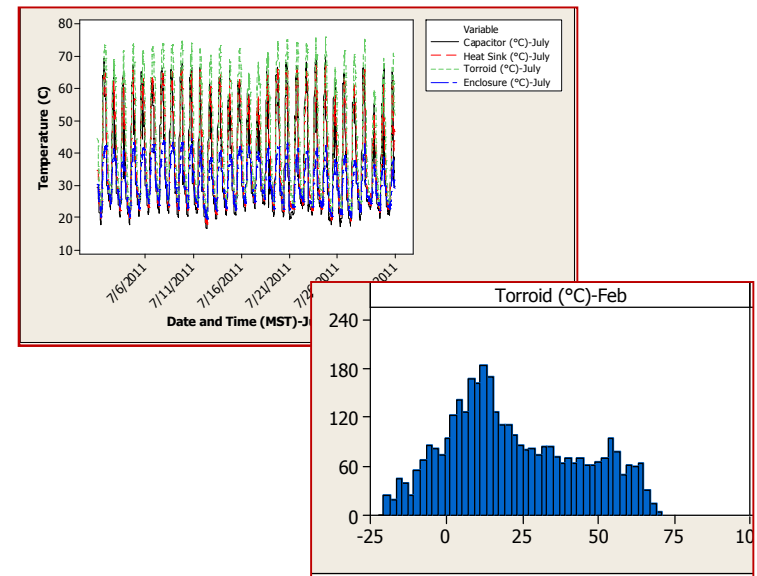
- Linear (time compressions),
- Increased temperature range
- Frequency analysis (rainflow counting)

## ➤ Voltage

- Linear (must understand relationship)

## ➤ Humidity

- Tends to be complex (adsorbed water)



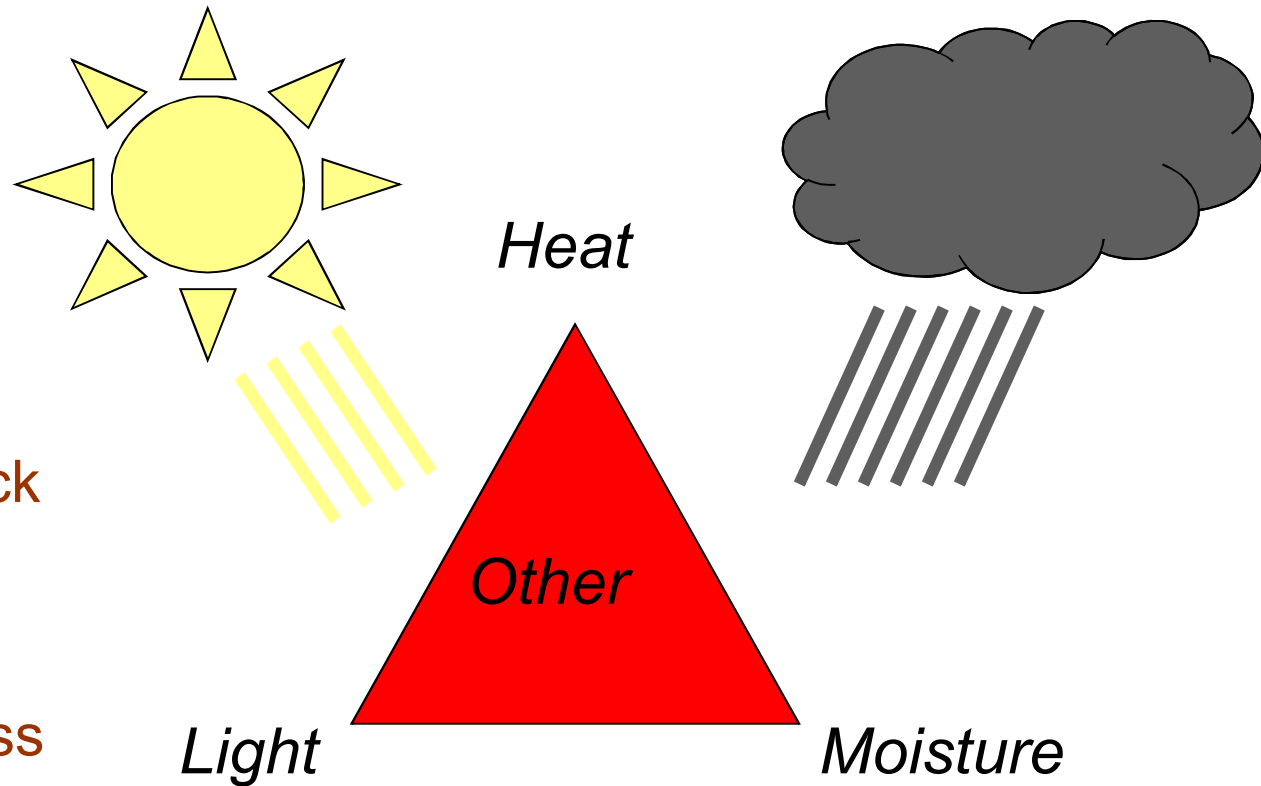
# Issues with ALT

- Unknown failure mechanisms
- Unknown / variable use environment
- Changing mechanisms as function of environmental stress
- Difficult to control and characterize defects
- Long duration experiments
- Evolving / improving technology



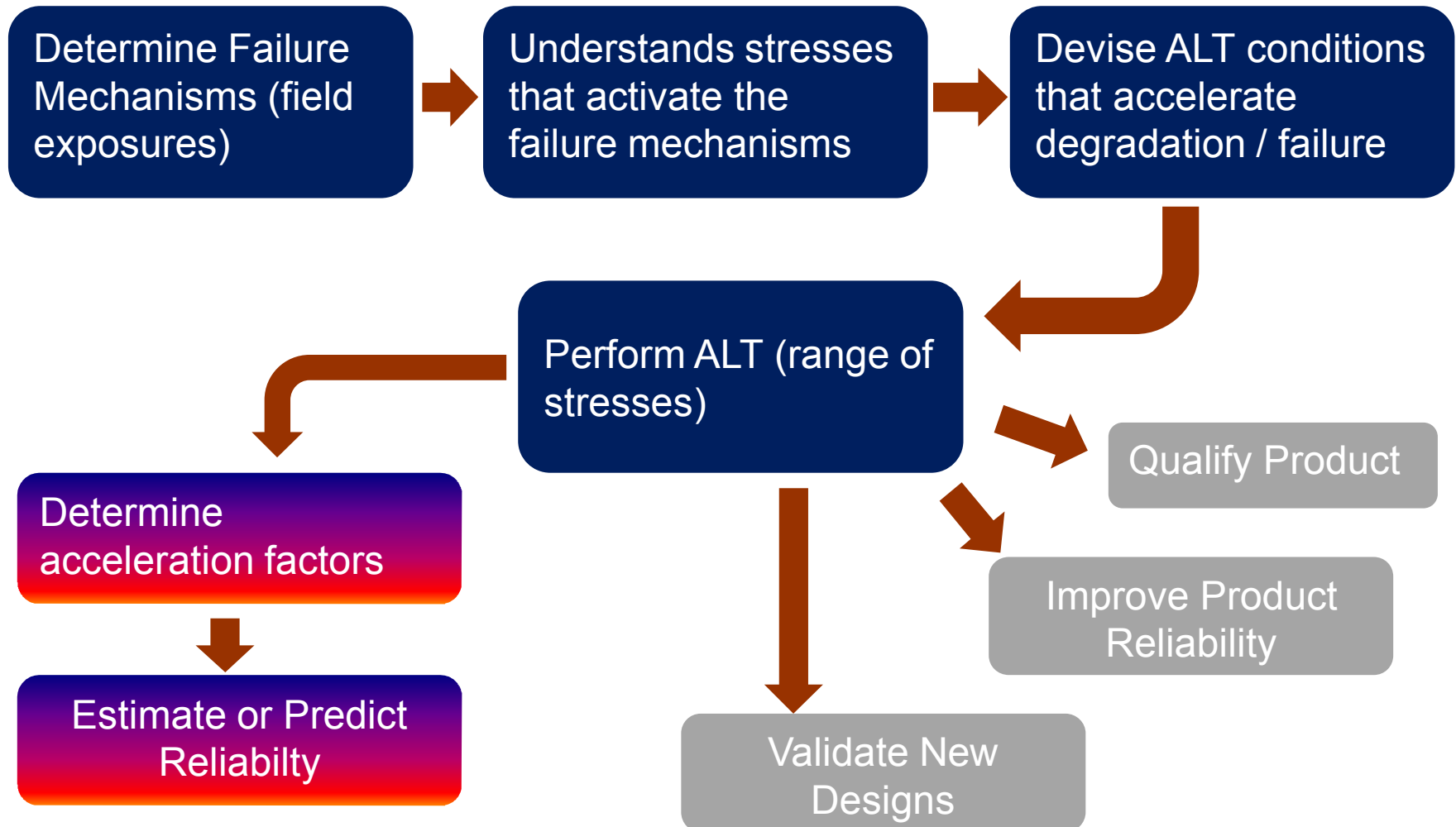
# What are the likely stresses that lead to Inverter Failure?

- Voltage
- Temperature
- Thermal cycling
- Thermal Shock
- Vibration
- Mechanical Shock
- Humidity
- Contamination
- Mechanical Stress
- ???
- ???



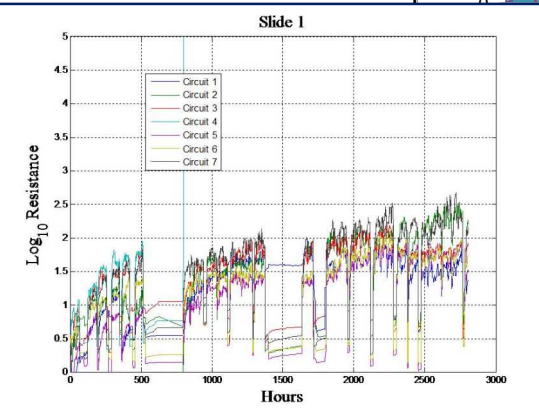
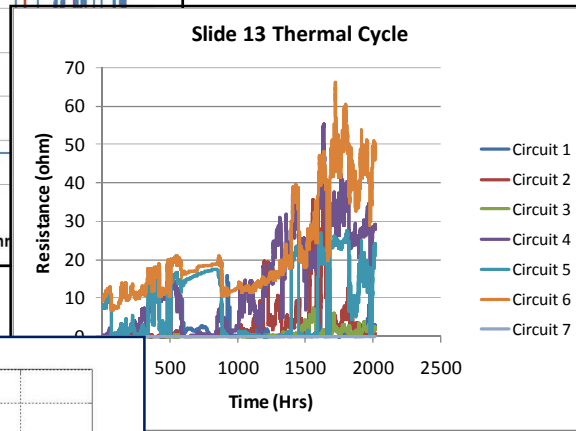
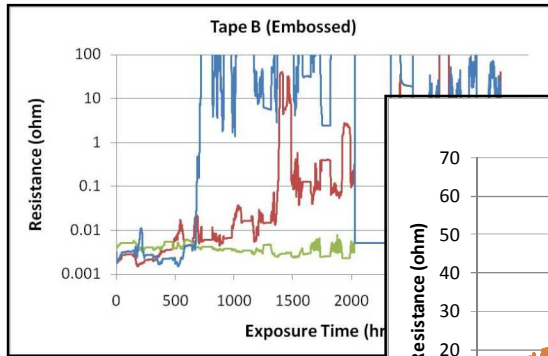


# How do we apply ALT to predicting end-of-life (wear out)?



# Analysis of metal foil tape degradation

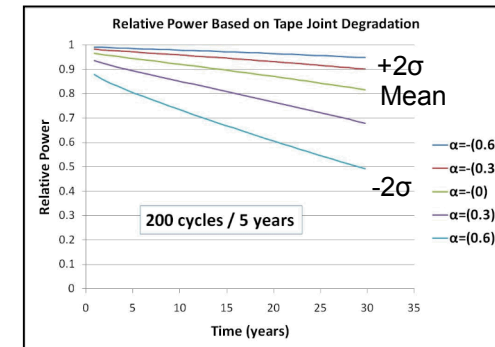
## Generate ALT data



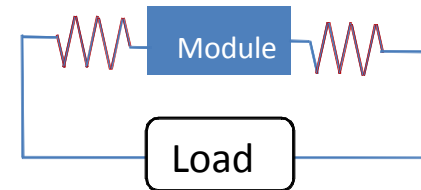
## Develop "acceleration factors"

$$R = 10^{(0.028(\sqrt{t}) + \alpha)}$$

## Apply acceleration factors to field

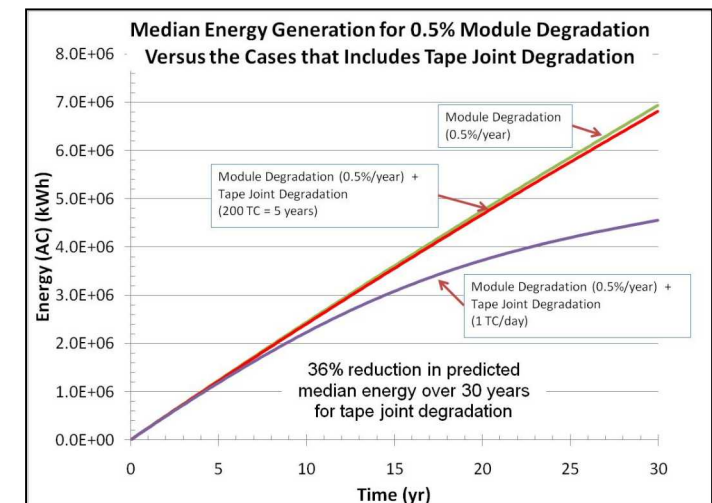


## Determine performance effect



$$E = I \times R$$

$$P = I \times V = I^2 \times R$$



# Summary

Accurate prediction of reliability is complex

- Requires understanding of degradation processes
- Data Driven
  - Field data
  - Accelerated testing
- Effect on performance (what is failure?)
- Includes uncertainty